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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	18MHz
Connectivity	I²C, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	14
Program Memory Size	2KB (2K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 3.6V
Data Converters	A/D 4x8b; D/A 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	16-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	16-TSSOP
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/p89lpc9171fdh-129

2.2 Additional features

- A high performance 80C51 CPU provides instruction cycle times of 111 ns to 222 ns for all instructions except multiply and divide when executing at 18 MHz. This is six times the performance of the standard 80C51 running at the same clock frequency. A lower clock frequency for the same performance results in power savings and reduced EMI.
- In-Application Programming (IAP-Lite) and byte erase allows code memory to be used for non-volatile data storage.
- Serial flash In-Circuit Programming (ICP) allows simple production coding with commercial EPROM programmers. Flash security bits prevent reading of sensitive application programs.
- Watchdog timer with separate on-chip oscillator, nominal 400 kHz, calibrated to ±5 %, requiring no external components. The watchdog prescaler is selectable from eight values.
- High-accuracy internal RC oscillator option, with clock doubler option, allows operation without external oscillator components. The RC oscillator option is selectable and fine tunable.
- Clock switching on the fly among internal RC oscillator, watchdog oscillator, external clock input provides optimal support of minimal power active mode with fast switching to maximum performance.
- Idle and two different power-down reduced power modes. Improved wake-up from Power-down mode (a LOW interrupt input starts execution). Typical power-down current is 1 μA (total power-down with voltage comparators disabled).
- Active-LOW reset. On-chip power-on reset allows operation without external reset components. A software reset function is also available.
- Configurable on-chip oscillator with frequency range options selected by user programmed flash configuration bits. Oscillator options support frequencies from 20 kHz to the maximum operating frequency of 18 MHz.
- Oscillator fail detect. The watchdog timer has a separate fully on-chip oscillator allowing it to perform an oscillator fail detect function.
- Programmable port output configuration options: quasi-bidirectional, open drain, push-pull, input-only.
- High current sourcing/sinking (20 mA) at 4 I/O pins on the P89LPC9151, 3 I/O pins on the P89LPC9161 and 5 I/O pins on the P89LPC9171. All other port pins have high sinking capability (20 mA). A maximum limit is specified for the entire chip.
- Port ‘input pattern match’ detect. Port 0 may generate an interrupt when the value of the pins match or do not match a programmable pattern.
- Controlled slew rate port outputs to reduce EMI. Outputs have approximately 10 ns minimum ramp times.
- Only power and ground connections are required to operate the P89LPC9151/9161/9171 when internal reset option is selected.
- Four interrupt priority levels.
- Five/six keypad interrupt inputs, plus two additional external interrupt inputs.
- Schmitt trigger port inputs.
- Second data pointer.
- Emulation support.

4. Block diagram

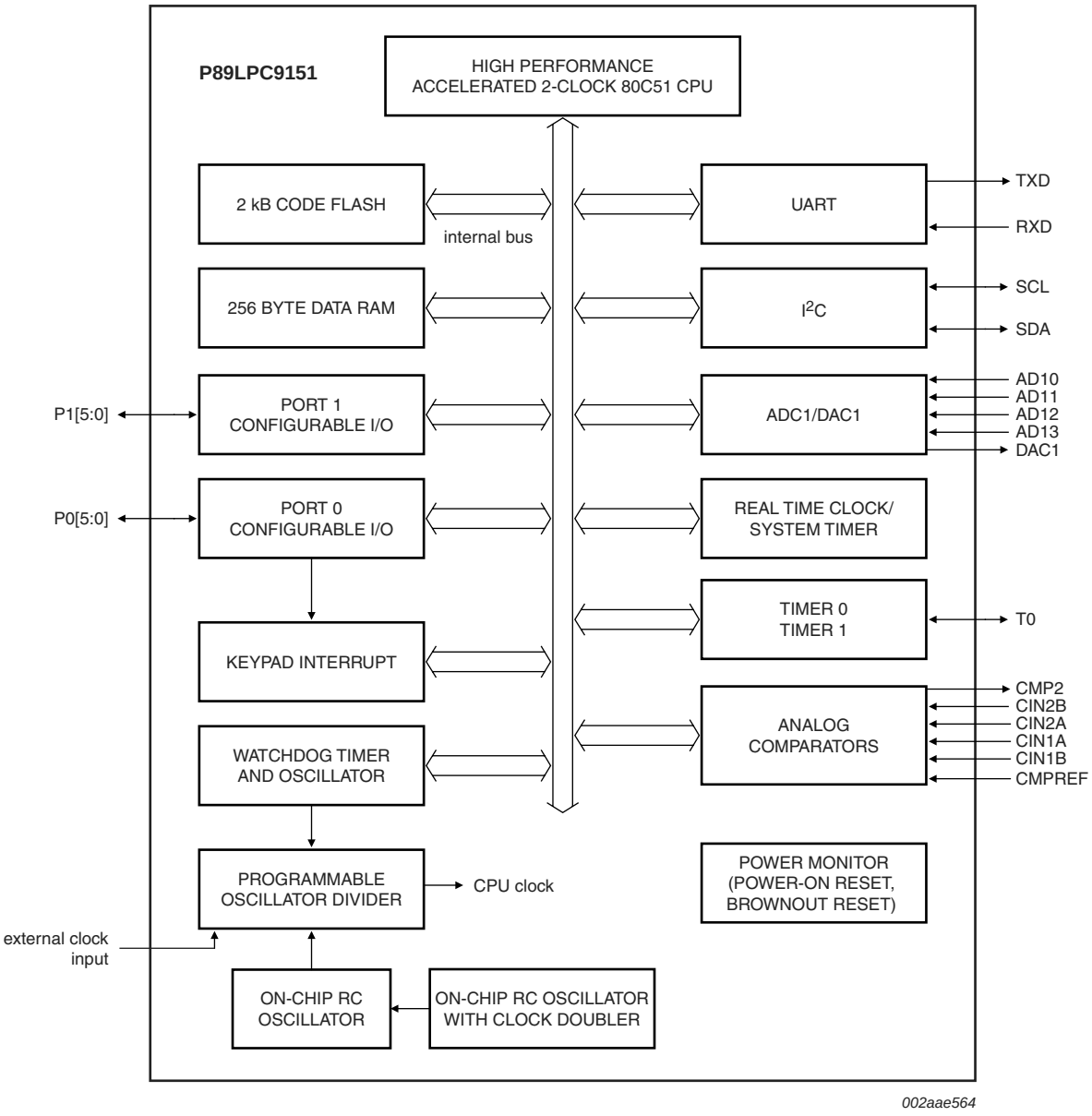


Fig 1. Block diagram (P89LPC9151)

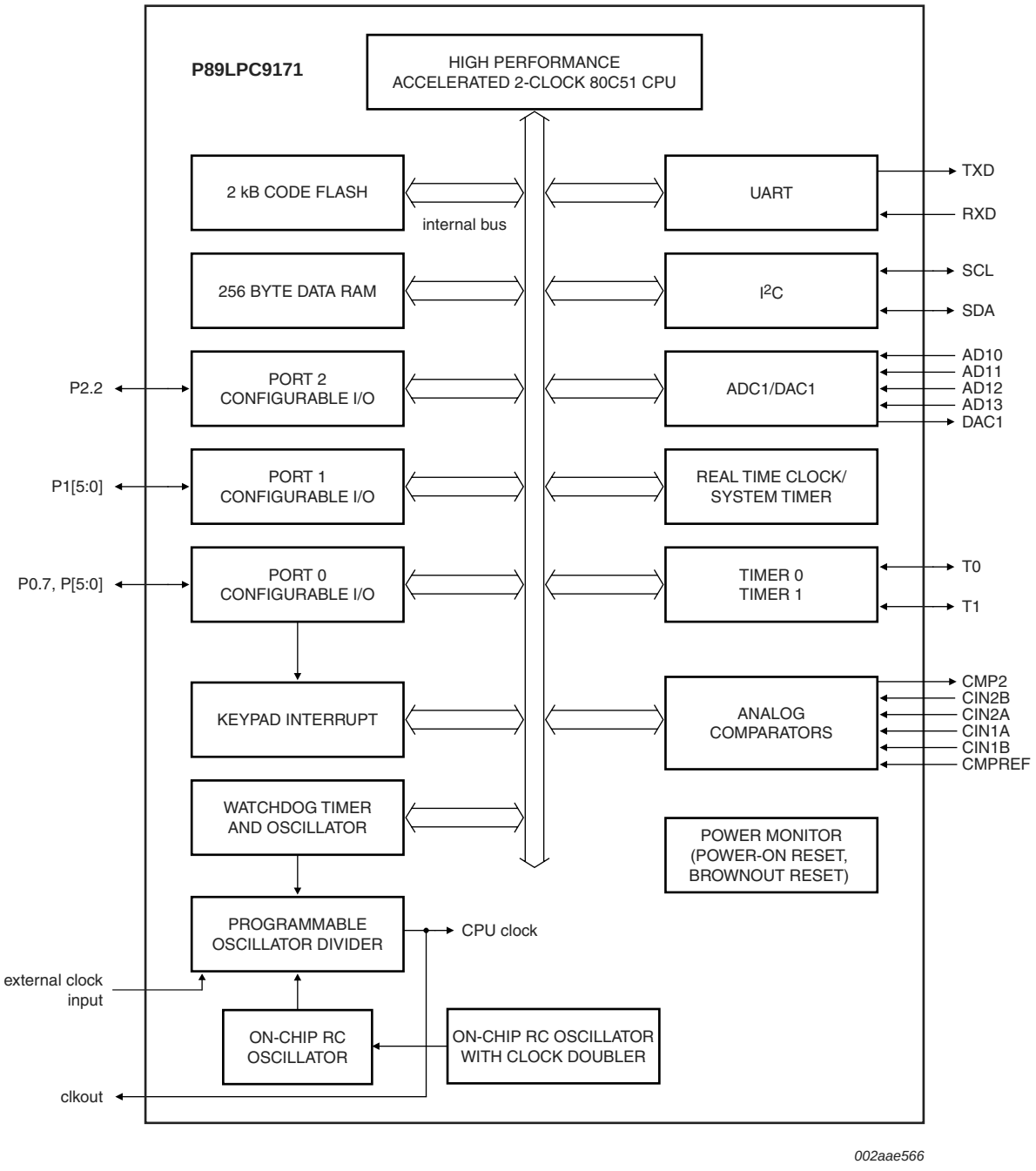


Fig 3. Block diagram (P89LPC9171)

Table 4. P89LPC9161 Pin description

Symbol	Pin	Type	Description
	TSSOP16		
P1.2/T0/SCL	8	I/O	**P1.2 —** Port 1 bit 2 (open-drain when used as output).
		I/O	**T0 —** Timer/counter 0 external count input or overflow output (open-drain when used as output).
		I/O	**SCL —** I^2C-bus serial clock input/output.
P1.3/$\overline{INT0}$/SDA	7	I/O	**P1.3 —** Port 1 bit 3 (open-drain when used as output).
		I	**$\overline{INT0}$ —** External interrupt 0 input.
		I/O	**SDA —** I^2C-bus serial data input/output.
P1.5/$\overline{RST}$	3	I	**P1.5 —** Port 1 bit 5 (input only).
		I	**$\overline{RST}$ —** External Reset input during power-on or if selected via UCFG1. When functioning as a reset input, a LOW on this pin resets the microcontroller, causing I/O ports and peripherals to take on their default states, and the processor begins execution at address 0. Also used during a power-on sequence to force ISP mode.
P2.2 to P2.5		I/O	**Port 2:** Port 2 is an 4-bit I/O port with a user-configurable output type. During reset Port 2 latches are configured in the input only mode with the internal pull-up disabled. The operation of Port 2 pins as inputs and outputs depends upon the port configuration selected. Each port pin is configured independently. Refer to Section 7.15 “I/O ports” for details. All pins have Schmitt trigger inputs. Port 2 also provides various special functions as described below:
P2.2/MOSI	6	I/O	**P2.2 —** Port 2 bit 2.
		I/O	**MOSI —** SPI master out slave in. When configured as master, this pin is output; when configured as slave, this pin is input.
P2.3/MISO	5	I/O	**P2.3 —** Port 2 bit 3.
		I/O	**MISO —** When configured as master, this pin is input, when configured as slave, this pin is output.
P2.4/$\overline{SS}$	2	I/O	**P2.4 —** Port 2 bit 4.
		I	**$\overline{SS}$ —** SPI Slave select.
P2.5/SPICLK	11	I/O	**P2.5 —** Port 2 bit 5.
		I/O	**SPICLK —** SPI clock. When configured as master, this pin is output; when configured as slave, this pin is input.
V_{SS}	4	I	**Ground:** 0 V reference.
V_{DD}	12	I	**Power supply:** This is the power supply voltage for normal operation as well as Idle and Power-down modes.

[1] Input/output for P1.0 to P1.3. Input for P1.5.

Table 10. Special function registers - P89LPC9171

** indicates SFRs that are bit addressable.*

Name	Description	SFR addr.	Bit functions and addresses								Reset value	
			MSB							LSB	Hex	Binary
BRGR1[2]	Baud rate generator 0 rate high	BFH									00	0000 0000
BRGCON	Baud rate generator 0 control	BDH	-	-	-	-	-	-	SBRGS	BRGEN	00[2]	xxxx xx00
CMP1	Comparator 1 control register	ACH	-	-	CE1	CP1	CN1	-	CO1	CMF1	00[1]	xx00 0000
CMP2	Comparator 2 control register	ADH	-	-	CE2	CP2	CN2	OE2	CO2	CMF2	00[1]	xx00 0000
DIVM	CPU clock divide-by-M control	95H									00	0000 0000
DPTR	Data pointer (2 bytes)											
DPH	Data pointer high	83H									00	0000 0000
DPL	Data pointer low	82H									00	0000 0000
FMADRH	Program flash address high	E7H									00	0000 0000
FMADRL	Program flash address low	E6H									00	0000 0000
FMCON	Program flash control (Read)	E4H	BUSY	-	-	-	HVA	HVE	SV	OI	70	0111 0000
	Program flash control (Write)	E4H	FMCMD.7	FMCMD.6	FMCMD.5	FMCMD.4	FMCMD.3	FMCMD.2	FMCMD.1	FMCMD.0		
FMDATA	Program flash data	E5H									00	0000 0000
I2ADR	I^2C-bus slave address register	DBH	I2ADR.6	I2ADR.5	I2ADR.4	I2ADR.3	I2ADR.2	I2ADR.1	I2ADR.0	GC	00	0000 0000

Or, for example, the parity bit (P, in the PSW) could be moved into TB8. When data is received, the 9th data bit goes into RB8 in special function register SCON, while the stop bit is not saved. The baud rate is programmable to either $1/16$ or $1/32$ of the CPU clock frequency, as determined by the SMOD1 bit in PCON.

7.21.4 Mode 3

11 bits are transmitted (through TXD) or received (through RXD): a start bit (logic 0), 8 data bits (LSB first), a programmable 9th data bit, and a stop bit (logic 1). In fact, Mode 3 is the same as Mode 2 in all respects except baud rate. The baud rate in Mode 3 is variable and is determined by the Timer 1 overflow rate or the baud rate generator (described in Section 7.21.5 “Baud rate generator and selection”).

7.21.5 Baud rate generator and selection

The P89LPC9151/9161/9171 enhanced UART has an independent baud rate generator. The baud rate is determined by a baud-rate preprogrammed into the BRGR1 and BRGR0 SFRs which together form a 16-bit baud rate divisor value that works in a similar manner as Timer 1 but is much more accurate. If the baud rate generator is used, Timer 1 can be used for other timing functions.

The UART can use either Timer 1 or the baud rate generator output (see Figure 12). Note that Timer T1 is further divided by 2 if the SMOD1 bit (PCON.7) is cleared. The independent baud rate generators use OSCCLK.

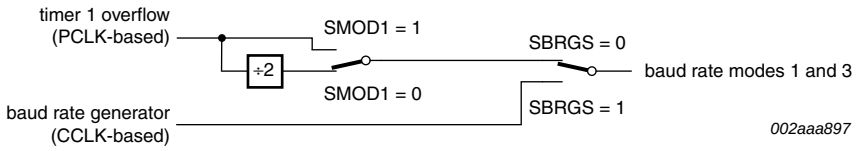


Fig 12. Baud rate sources for UART (Modes 1, 3)

7.21.6 Framing error

Framing error is reported in the status register (SSTAT). In addition, if SMOD0 (PCON.6) is logic 1, framing errors can be made available in SCON.7 respectively. If SMOD0 is logic 0, SCON.7 is SM0. It is recommended that SM0 and SM1 (SCON.7:6) are set up when SMOD0 is logic 0.

7.21.7 Break detect

Break detect is reported in the status register (SSTAT). A break is detected when 11 consecutive bits are sensed LOW. The break detect can be used to reset the device and force the device into ISP mode.

7.21.8 Double buffering

The UART has a transmit double buffer that allows buffering of the next character to be written to SBUF while the first character is being transmitted. Double buffering allows transmission of a string of characters with only one stop bit between any two characters, as long as the next character is written between the start bit and the stop bit of the previous character.

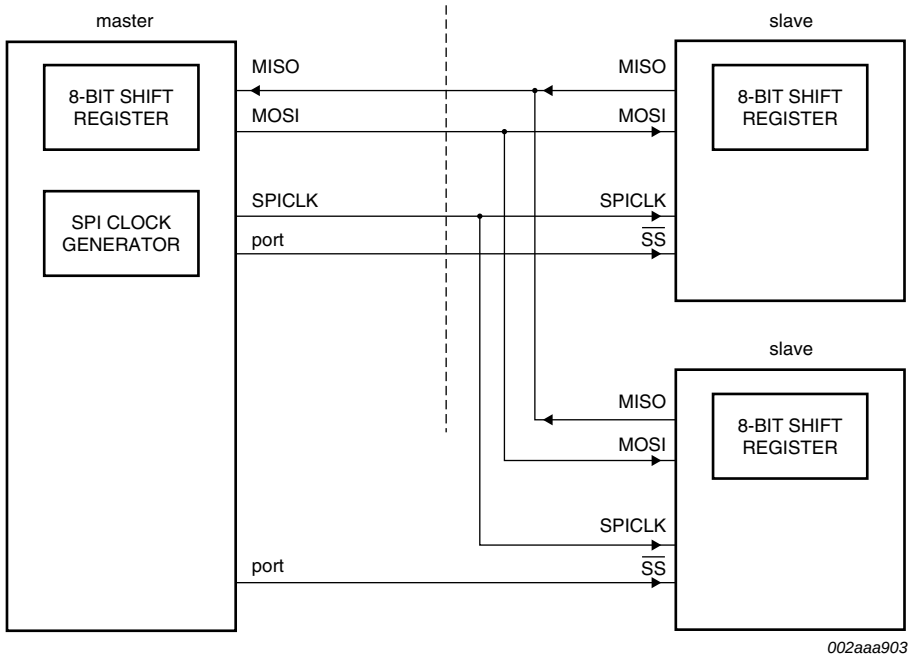


Fig 18. SPI single master multiple slaves configuration

7.24 Analog comparators

Two analog comparators are provided on the P89LPC9151/9161/9171. Input and output options allow use of the comparators in a number of different configurations. Comparator operation is such that the output is a logical one (which may be read in a register and/or routed to a pin) when the positive input (one of two selectable inputs) is greater than the negative input (selectable from a pin or an internal reference voltage). Otherwise the output is a zero. Each comparator may be configured to cause an interrupt when the output value changes. Comparator 1 may be output to a port pin.

The overall connections to both comparators are shown in Figure 19. The comparators function to V_{DD} = 2.4 V.

When each comparator is first enabled, the comparator output and interrupt flag are not guaranteed to be stable for 10 μs. The corresponding comparator interrupt should not be enabled during that time, and the comparator interrupt flag must be cleared before the interrupt is enabled in order to prevent an immediate interrupt service.

When a comparator is disabled the comparator's output, COn, goes HIGH. If the comparator output was LOW and then is disabled, the resulting transition of the comparator output from a LOW to HIGH state will set the comparator flag, CMFn. This will cause an interrupt if the comparator interrupt is enabled. The user should therefore disable the comparator interrupt prior to disabling the comparator. Additionally, the user should clear the comparator flag, CMFn, after disabling the comparator.

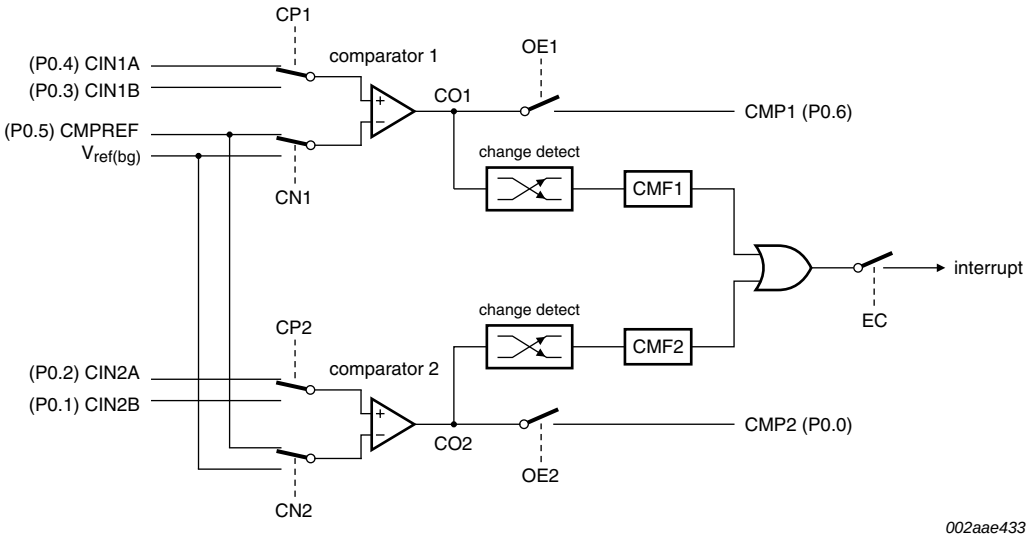


Fig 19. Comparator input and output connections

7.24.1 Internal reference voltage

An internal reference voltage generator may supply a default reference when a single comparator input pin is used. The value of the internal reference voltage, referred to as $V_{ref(bg)}$, is 1.23 V ± 10 %.

7.24.2 Comparator interrupt

Each comparator has an interrupt flag contained in its configuration register. This flag is set whenever the comparator output changes state. The flag may be polled by software or may be used to generate an interrupt. The two comparators use one common interrupt vector. If both comparators enable interrupts, after entering the interrupt service routine, the user needs to read the flags to determine which comparator caused the interrupt.

7.24.3 Comparators and power reduction modes

Either or both comparators may remain enabled when Power-down or Idle mode is activated, but both comparators are disabled automatically in Total Power-down mode.

If a comparator interrupt is enabled (except in Total Power-down mode), a change of the comparator output state will generate an interrupt and wake-up the processor. If the comparator output to a pin is enabled, the pin should be configured in the push-pull mode in order to obtain fast switching times while in Power-down mode. The reason is that with the **oscillator** stopped, the temporary strong pull-up that normally occurs during switching on a quasi-bidirectional port pin does not take place.

Comparators consume power in Power-down and Idle modes, as well as in the normal operating mode. This fact should be taken into account when system power consumption is an issue. To minimize power consumption, the user can disable the comparators via PCONA.5, or put the device in Total Power-down mode.

7.25 KBI

The Keypad Interrupt function (KBI) is intended primarily to allow a single interrupt to be generated when Port 0 is equal to or not equal to a certain pattern. This function can be used for bus address recognition or keypad recognition. The user can configure the port via SFRs for different tasks.

The Keypad Interrupt Mask Register (KBMASK) is used to define which input pins connected to Port 0 can trigger the interrupt. The Keypad Pattern Register (KBPATN) is used to define a pattern that is compared to the value of Port 0. The Keypad Interrupt Flag (KBIF) in the Keypad Interrupt Control Register (KBCON) is set when the condition is matched while the Keypad Interrupt function is active. An interrupt will be generated if enabled. The PATN_SEL bit in the Keypad Interrupt Control Register (KBCON) is used to define equal or not-equal for the comparison.

In order to use the Keypad Interrupt as an original KBI function like in 87LPC76x series, the user needs to set KBPATN = 0FFH and PATN_SEL = 1 (not equal), then any key connected to Port 0 which is enabled by the KBMASK register will cause the hardware to set KBIF and generate an interrupt if it has been enabled. The interrupt may be used to wake-up the CPU from Idle or Power-down modes. This feature is particularly useful in handheld, battery-powered systems that need to carefully manage power consumption yet also need to be convenient to use.

In order to set the flag and cause an interrupt, the pattern on Port 0 must be held longer than six CCLKs.

7.26 Watchdog timer

The watchdog timer causes a system reset when it underflows as a result of a failure to feed the timer prior to the timer reaching its terminal count. It consists of a programmable 12-bit prescaler, and an 8-bit down counter. The down counter is decremented by a tap taken from the prescaler. The clock source for the prescaler can be the PCLK, or the nominal 400 kHz watchdog oscillator. The watchdog timer can only be reset by a power-on reset. When the watchdog feature is disabled, it can be used as an interval timer and may generate an interrupt. Figure 20 shows the watchdog timer in Watchdog mode. Feeding the watchdog requires a two-byte sequence. If PCLK is selected as the watchdog clock and the CPU is powered down, the watchdog is disabled. The watchdog timer has a time-out period that ranges from a few μs to a few seconds. Please refer to the P89LPC9151/9161/9171 *User manual* for more details.

- ◆ Edge triggered.
- 8-bit conversion time of ≥ 1.61 μs at an A/D clock of 8.0 MHz.
- Interrupt or polled operation.
- Boundary limits interrupt.
- DAC output to a port pin with high output impedance.
- Clock divider.
- Power-down mode.

8.3 Block diagram

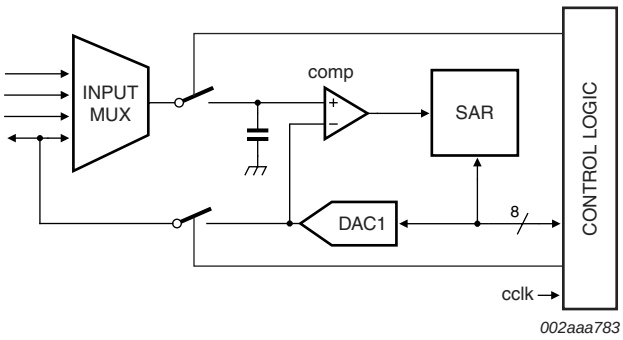


Fig 21. ADC block diagram

8.4 ADC operating modes

8.4.1 Fixed channel, single conversion mode

A single input channel can be selected for conversion. A single conversion will be performed and the result placed in the result register which corresponds to the selected input channel. An interrupt, if enabled, will be generated after the conversion completes.

8.4.2 Fixed channel, continuous conversion mode

A single input channel can be selected for continuous conversion. The results of the conversions will be sequentially placed in the four result register. The user may select whether an interrupt can be generated after every four conversions. Additional conversion results will again cycle through the four result register, overwriting the previous results. Continuous conversions continue until terminated by the user.

8.4.3 Auto scan, single conversion mode

Any combination of the four input channels can be selected for conversion. A single conversion of each selected input will be performed and the result placed in the result register which corresponds to the selected input channel. An interrupt, if enabled, will be generated after all selected channels have been converted. If only a single channel is selected this is equivalent to single channel, single conversion mode.

8.4.4 Auto scan, continuous conversion mode

Any combination of the four input channels can be selected for conversion. A conversion of each selected input will be performed and the result placed in the result register which corresponds to the selected input channel. An interrupt, if enabled, will be generated after

9. Limiting values

Table 15. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).[1]

Symbol	Parameter	Conditions		Min	Max	Unit
$T_{amb(bias)}$	bias ambient temperature			−55	+125	°C
T_{stg}	storage temperature			−65	+150	°C
$I_{OH(I/O)}$	HIGH-level output current per input/output pin			-	20	mA
$I_{OL(I/O)}$	LOW-level output current per input/output pin			-	20	mA
$I_{I/Otot(max)}$	maximum total input/output current			-	100	mA
V_{xtal}	crystal voltage	on XTAL1, XTAL2; pin to V_{SS}		-	V_{DD} + 0.5	V
V_n	voltage on any other pin	except XTAL1, XTAL2; pin to V_{SS}		−0.5	+5.5	V
$P_{tot(pack)}$	total power dissipation (per package)	based on package heat transfer, not device power consumption		-	1.5	W
V_{ESD}	electrostatic discharge voltage	human body model; all pins	[2]	−3000	+3000	
		charged device model; all pins		−700	+700	

[1] The following applies to Table 15:

a) This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maximum.

b) Parameters are valid over ambient temperature range unless otherwise specified. All voltages are with respect to V_{SS} unless otherwise noted.

[2] Human body model: equivalent to discharging a 100 pF capacitor through a 1.5 kΩ series resistor.

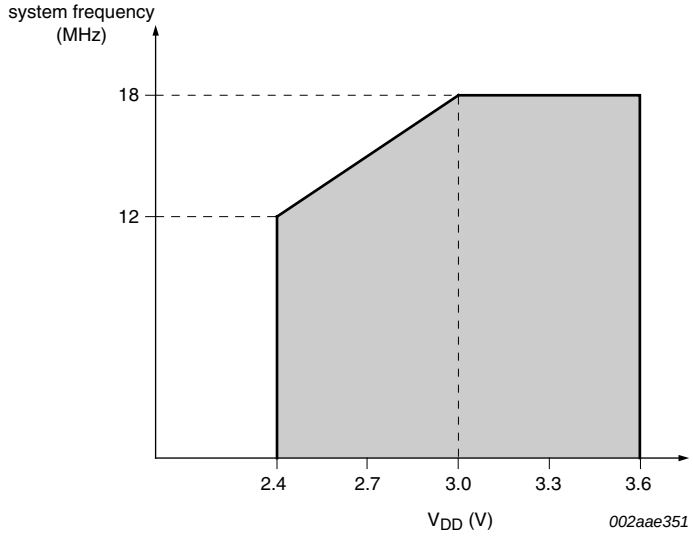


Fig 22. Frequency versus supply voltage

10. Static characteristics

Table 16. Static characteristics

V_{DD} = 2.4 V to 3.6 V unless otherwise specified.
T_{amb} = −40 °C to +85 °C for industrial applications, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
$I_{DD(oper)}$	operating supply current	V_{DD} = 3.6 V; f_{osc} = 12 MHz	[2]	-	10	15	mA
		V_{DD} = 3.6 V; f_{osc} = 18 MHz	[2]	-	14	23	mA
$I_{DD(idle)}$	Idle mode supply current	V_{DD} = 3.6 V; f_{osc} = 12 MHz	[3]	-	3.25	5	mA
		V_{DD} = 3.6 V; f_{osc} = 18 MHz	[3]	-	5	7	mA
$I_{DD(pd)}$	Power-down mode supply current	V_{DD} = 3.6 V; voltage comparators powered down	[4]	-	20	40	μA
$I_{DD(tpd)}$	total Power-down mode supply current	V_{DD} = 3.6 V	[5]	-	1	5	μA
$(dV/dt)_r$	rise rate	of V_{DD}; to ensure POR signal		5	-	5000	V/S
V_{DDR}	data retention supply voltage			1.5	-	-	V
$V_{th(HL)}$	HIGH-LOW threshold voltage	except SCL, SDA		$0.22V_{DD}$	$0.4V_{DD}$	-	V
V_{IL}	LOW-level input voltage	SCL, SDA only		−0.5	-	$0.3V_{DD}$	V
$V_{th(LH)}$	LOW-HIGH threshold voltage	except SCL, SDA		-	$0.6V_{DD}$	$0.7V_{DD}$	V
V_{IH}	HIGH-level input voltage	SCL, SDA only		$0.7V_{DD}$	-	5.5	V
V_{hys}	hysteresis voltage	port 1		-	$0.2V_{DD}$	-	V
V_{OL}	LOW-level output voltage	I_{OL} = 20 mA; V_{DD} = 2.4 V to 3.6 V all ports, all modes except high-Z	[6]	-	0.6	1.0	V
		I_{OL} = 3.2 mA; V_{DD} = 2.4 V to 3.6 V all ports, all modes except high-Z	[6]	-	0.2	0.3	V
V_{OH}	HIGH-level output voltage	I_{OH} = −20 μA; V_{DD} = 2.4 V to 3.6 V; all ports, quasi-bidirectional mode		V_{DD} − 0.3	V_{DD} − 0.2	-	V
		I_{OH} = −3.2 mA; V_{DD} = 2.4 V to 3.6 V; all ports, push-pull mode		V_{DD} − 0.7	V_{DD} − 0.4	-	V
		I_{OH} = −10 mA; V_{DD} = 2.4 V to 3.6 V; all ports, push-pull mode		-	3.2	-	V
V_n	voltage on any other pin	except V_{DD}; with respect to V_{SS}	[7]	−0.5	-	+5.5	V
C_{iss}	input capacitance		[8]	-	-	15	pF
I_{IL}	LOW-level input current	V_I = 0.4 V	[9]	-	-	−80	μA
I_{LI}	input leakage current	$V_I = V_{IL}$, V_{IH}, or $V_{th(HL)}$	[10]	-	-	±1	μA
I_{THL}	HIGH-LOW transition current	all ports; V_I = 1.5 V at V_{DD} = 3.6 V	[11]	−30	-	−450	μA

Table 16. Static characteristics *…continued*
V_{DD} = 2.4 V to 3.6 V unless otherwise specified.
T_{amb} = −40 °C to +85 °C for industrial applications, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
$R_{RST\_N(int)}$	internal pull-up resistance on pin $\overline{RST}$	pin $\overline{RST}$	10	-	30	kΩ
$V_{ref(bg)}$	band gap reference voltage		1.11	1.23	1.34	V
TC_{bg}	band gap temperature coefficient		-	10	20	ppm/°C

[1] Typical ratings are not guaranteed. The values listed are at room temperature, 3 V.

[2] The $I_{DD(oper)}$ specification is measured using an external clock with code while(1) {} executed from on-chip flash.

[3] The $I_{DD(idle)}$ specification is measured using an external clock with no active peripherals, with the following functions disabled: real-time clock and watchdog timer.

[4] The $I_{DD(pd)}$ specification is measured using internal RC oscillator with the following functions disabled: comparators, real-time clock, and watchdog timer.

[5] The $I_{DD(tpd)}$ specification is measured using an external clock with the following functions disabled: comparators, real-time clock, brownout detect, and watchdog timer.

[6] See Section 9 “Limiting values” for steady state (non-transient) limits on I_{OL} or I_{OH}. If I_{OL}/I_{OH} exceeds the test condition, V_{OL}/V_{OH} may exceed the related specification.

[7] This specification can be applied to pins which have A/D input or analog comparator input functions when the pin is not being used for those analog functions. When the pin is being used as an analog input pin, the maximum voltage on the pin must be limited to 4.0 V with respect to V_{SS}.

[8] Pin capacitance is characterized but not tested.

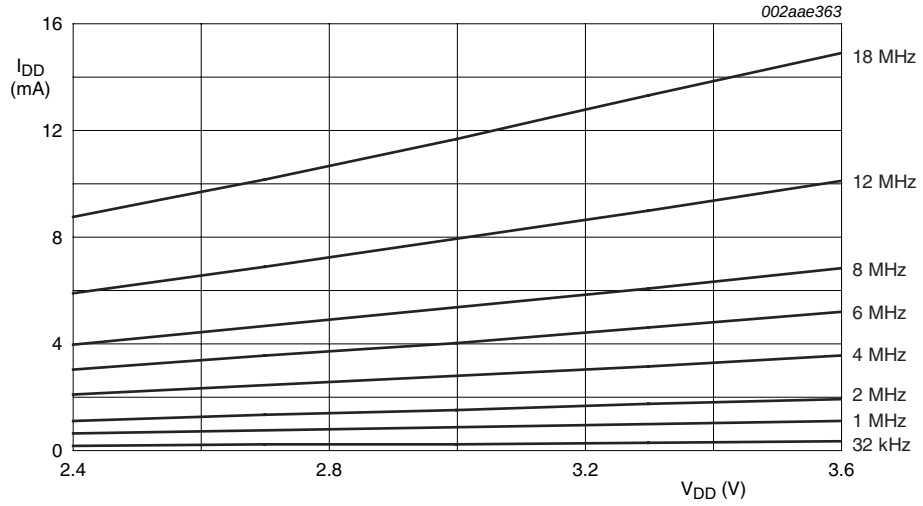
[9] Measured with port in quasi-bidirectional mode.

[10] Measured with port in high-impedance mode.

[11] Port pins source a transition current when used in quasi-bidirectional mode and externally driven from logic 1 to logic 0. This current is highest when V_I is approximately 2 V.

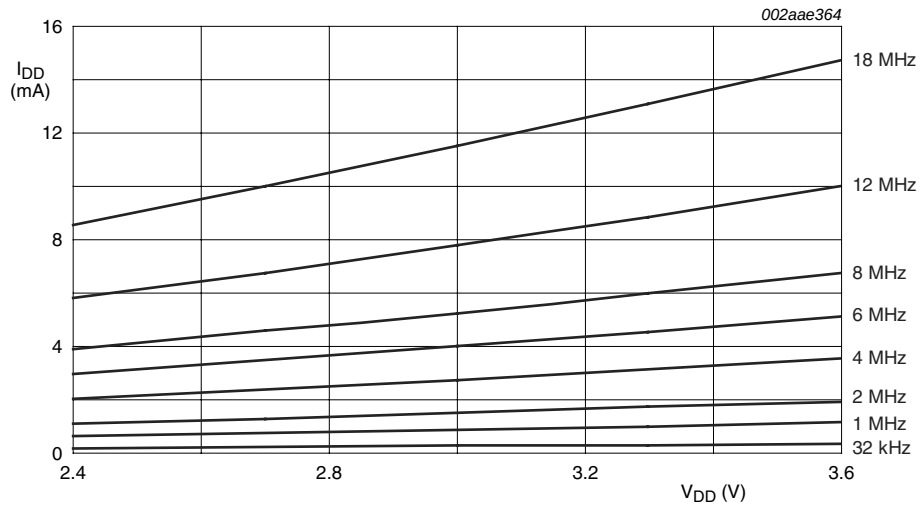
10.1 Current characteristics

Note: The graphs provided are a statistical summary based on a limited number of samples and only for information purposes. The performance characteristics listed are not tested or guaranteed.



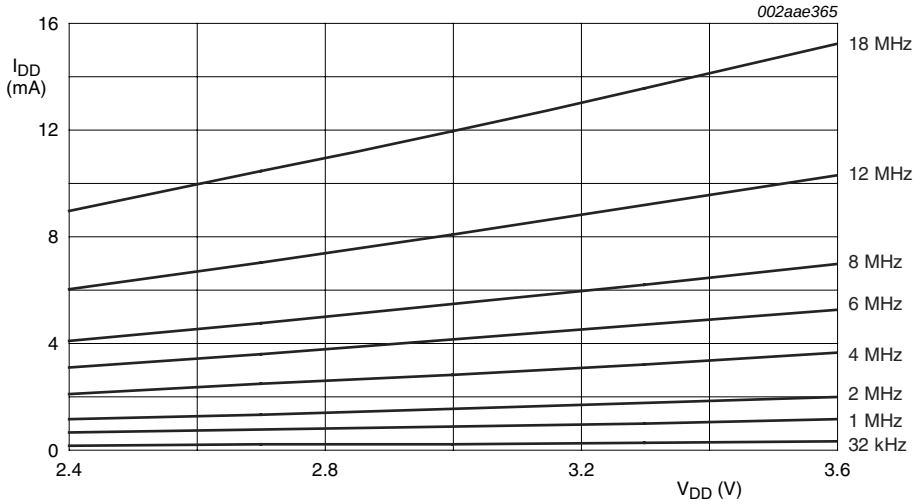
Test conditions: normal mode, code while(1) {} executed from on-chip flash; using an external clock.

Fig 23. $I_{DD(oper)}$ versus frequency at +25 °C



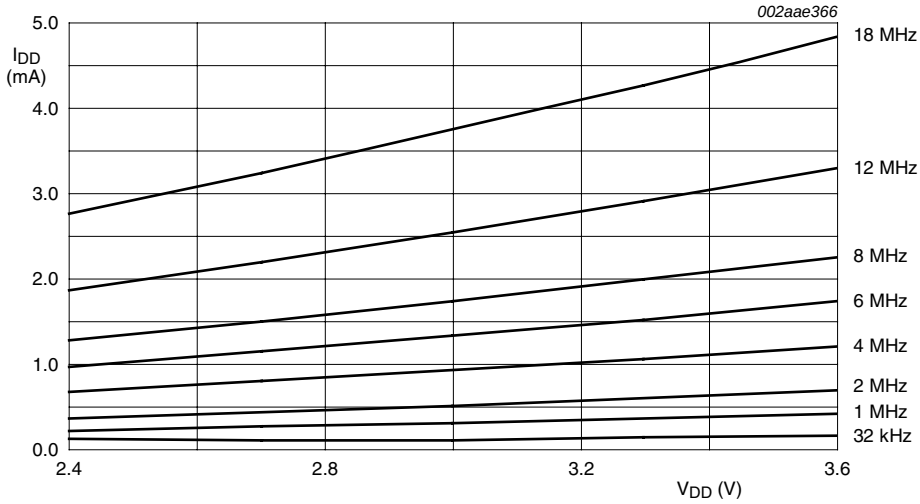
Test conditions: normal mode, code while(1) {} executed from on-chip flash; using an external clock.

Fig 24. $I_{DD(oper)}$ versus frequency at −40 °C



Test conditions: normal mode, code while(1) {} executed from on-chip flash; using an external clock.

Fig 25. $I_{DD(oper)}$ versus frequency at +85 °C



Test conditions: idle mode entered executing code from on-chip flash; using an external clock with no active peripherals, with the following functions disabled: real-time clock and watchdog timer.

Fig 26. $I_{DD(idle)}$ versus frequency at +25 °C

11. Dynamic characteristics

Table 18. Dynamic characteristics (12 MHz)

V_{DD} = 2.4 V to 3.6 V unless otherwise specified.

T_{amb} = −40 °C to +85 °C for industrial applications, unless otherwise specified.[1][2]

Symbol	Parameter	Conditions	Variable clock		f_{osc} = 12 MHz		Unit
			Min	Max	Min	Max	
$f_{osc(RC)}$	internal RC oscillator frequency	nominal f = 7.3728 MHz trimmed to ±1 % at T_{amb} = 25 °C; clock doubler option = OFF (default)	7.189	7.557	7.189	7.557	MHz
		nominal f = 14.7456 MHz; clock doubler option = ON, V_{DD} = 2.7 V to 3.6 V	14.378	15.114	14.378	15.114	MHz
$f_{osc(WD)}$	internal watchdog oscillator frequency	T_{amb} = 25 °C	380	420	380	420	kHz
f_{osc}	oscillator frequency		0	12	-	-	MHz
$T_{cy(clk)}$	clock cycle time	see Figure 38	83	-	-	-	ns
f_{CLKLP}	low-power select clock frequency		0	8	-	-	MHz
Glitch filter							
t_{gr}	glitch rejection time	P1.5/$\overline{\text{RST}}$ pin	-	50	-	50	ns
		any pin except P1.5/$\overline{\text{RST}}$	-	15	-	15	ns
t_{sa}	signal acceptance time	P1.5/$\overline{\text{RST}}$ pin	125	-	125	-	ns
		any pin except P1.5/$\overline{\text{RST}}$	50	-	50	-	ns
External clock							
t_{CHCX}	clock HIGH time	see Figure 38	33	$T_{cy(clk)} - t_{CLCX}$	33	-	ns
t_{CLCX}	clock LOW time	see Figure 38	33	$T_{cy(clk)} - t_{CHCX}$	33	-	ns
t_{CLCH}	clock rise time	see Figure 38	-	8	-	8	ns
t_{CHCL}	clock fall time	see Figure 38	-	8	-	8	ns
Shift register (UART mode 0)							
T_{XLXL}	serial port clock cycle time	see Figure 39	$16T_{cy(clk)}$	-	1333	-	ns
t_{QVXH}	output data set-up to clock rising edge time	see Figure 39	$13T_{cy(clk)}$	-	1083	-	ns
t_{XHQX}	output data hold after clock rising edge time	see Figure 39	-	$T_{cy(clk)}$ + 20	-	103	ns
t_{XHDX}	input data hold after clock rising edge time	see Figure 39	-	0	-	0	ns
t_{XHDV}	input data valid to clock rising edge time	see Figure 39	150	-	150	-	ns
SPI interface							
f_{SPI}	SPI operating frequency						
	slave		0	$^{CCLK}/_{6}$	0	2.0	MHz
	master		-	$^{CCLK}/_{4}$	-	3.0	MHz

Table 19. Dynamic characteristics (18 MHz) *…continued*
V_{DD} = 3.0 V to 3.6 V unless otherwise specified.
T_{amb} = −40 °C to +85 °C for industrial applications, unless otherwise specified.[1][2]

Symbol	Parameter	Conditions	Variable clock		f_{osc} = 18 MHz		Unit
			Min	Max	Min	Max	
$t_{SPILEAD}$	SPI enable lead time	see Figure 42, 43					
	slave		250	-	250	-	ns
t_{SPILAG}	SPI enable lag time	see Figure 42, 43					
	slave		250	-	250	-	ns
$t_{SPICLKH}$	SPICLK HIGH time	see Figure 40, 41, 42, 43					
	slave		$^{3}/_{CCLK}$	-	167	-	ns
	master		$^{2}/_{CCLK}$	-	111	-	ns
$t_{SPICLKL}$	SPICLK LOW time	see Figure 40, 41, 42, 43					
	slave		$^{3}/_{CCLK}$	-	167	-	ns
	master		$^{2}/_{CCLK}$	-	111	-	ns
t_{SPIDSU}	SPI data set-up time	see Figure 40, 41, 42, 43					
	master or slave		100	-	100	-	ns
t_{SPIDH}	SPI data hold time	see Figure 40, 41, 42, 43					
	master or slave		100	-	100	-	ns
t_{SPIA}	SPI access time	see Figure 42, 43					
	slave		0	80	0	80	ns
t_{SPIDIS}	SPI disable time	see Figure 42, 43					
	slave		0	160	-	160	ns
t_{SPIDV}	SPI enable to output data valid time	see Figure 40, 41, 42, 43					
	slave		-	160	-	160	ns
	master		-	111	-	111	ns
t_{SPIOH}	SPI output data hold time	see Figure 40, 41, 42, 43	0	-	0	-	ns
t_{SPIR}	SPI rise time	see Figure 40, 41, 42, 43					
	SPI outputs (SPICLK, MOSI, MISO)		-	100	-	100	ns
	SPI inputs (SPICLK, MOSI, MISO, $\overline{SS}$)		-	2000	-	2000	ns
t_{SPIF}	SPI fall time	see Figure 40, 41, 42, 43					
	SPI outputs (SPICLK, MOSI, MISO)		-	100	-	100	ns
	SPI inputs (SPICLK, MOSI, MISO, $\overline{SS}$)		-	2000	-	2000	ns

[1] Parameters are valid over operating temperature range unless otherwise specified.

[2] Parts are tested to 2 MHz, but are guaranteed to operate down to 0 Hz.

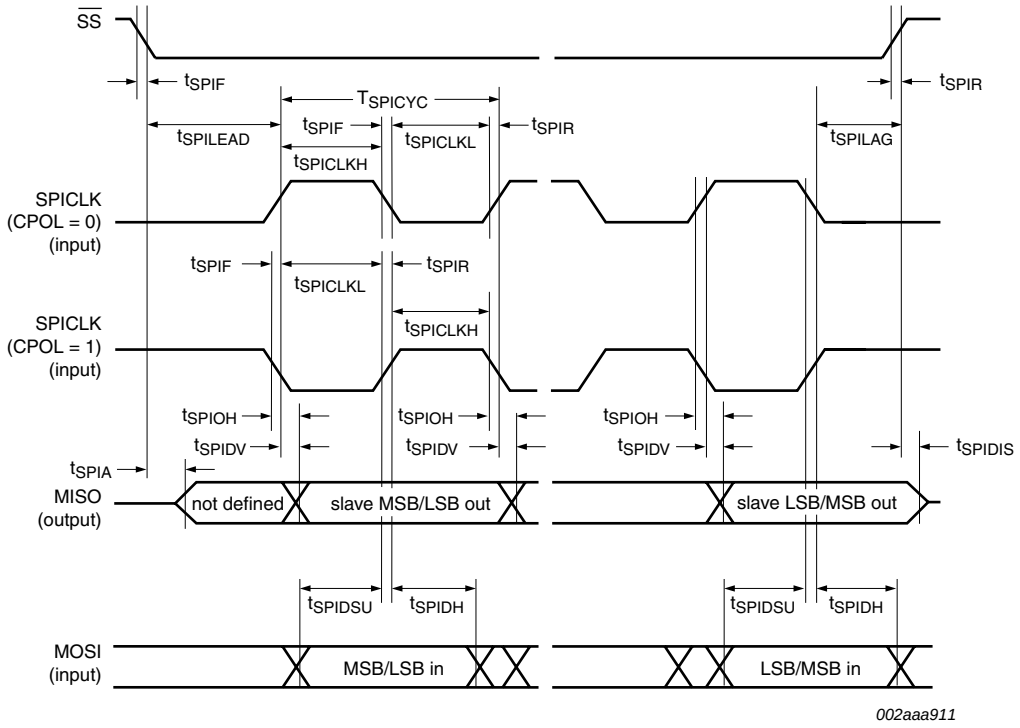


Fig 43. SPI slave timing (CPHA = 1)

12. Other characteristics

12.1 Comparator electrical characteristics

Table 20. Comparator electrical characteristics

V_{DD} = 2.4 V to 3.6 V, unless otherwise specified.

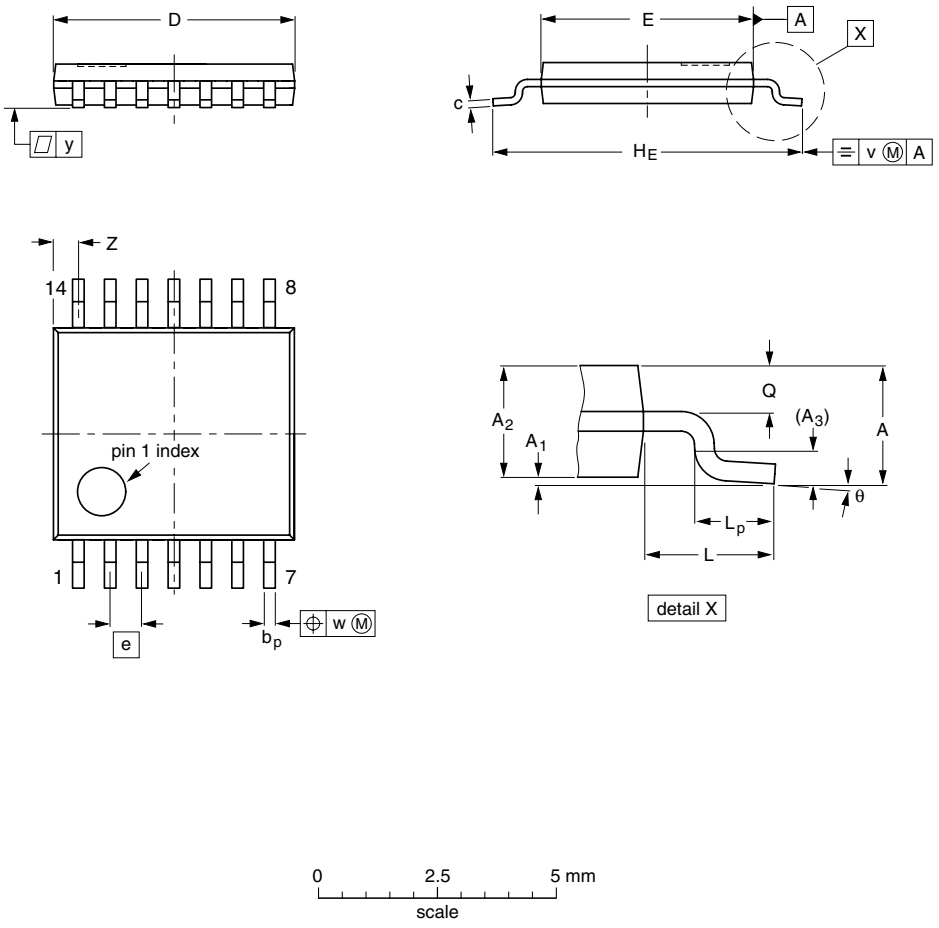
T_{amb} = –40 °C to +85 °C for industrial applications, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{IO}	input offset voltage			-	-	±20	mV
V_{IC}	common-mode input voltage			0	-	V_{DD} – 0.3	V
CMRR	common-mode rejection ratio		[1]	-	-	–50	dB
$t_{res(tot)}$	total response time			-	250	500	ns
$t_{(CE-OV)}$	chip enable to output valid time			-	-	10	µs
I_{LI}	input leakage current	0 V < V_I < V_{DD}		-	-	±1	µA

[1] This parameter is characterized, but not tested in production.

13. Package outline

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm **SOT402-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8^o 0^o

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT402-1		MO-153				~~99-12-27~~ 03-02-18

Fig 46. TSSOP14 package outline (SOT402-1)

14. Abbreviations

Table 22. Abbreviations

Acronym	Description
ADC	Analog to Digital Converter
BOD	Brownout Detection
CPU	Central Processing Unit
DAC	Digital to Analog Converter
EEPROM	Electrically Erasable Programmable Read-Only Memory
EPROM	Erasable Programmable Read-Only Memory
EMI	ElectroMagnetic Interference
IRC	Internal RC
LSB	Least Significant Bit
MSB	Most Significant Bit
PLL	Phase-Locked Loop
PWM	Pulse Width Modulator
RAM	Random Access Memory
RC	Resistance-Capacitance
RTC	Real-Time Clock
SAR	Successive Approximation Register
SCL	Serial Clock Line
SDA	Serial DAta line
SFR	Special Function Register
SPI	Serial Peripheral Interface
UART	Universal Asynchronous Receiver/Transmitter